

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Tao Deng et al.
Serial No.: 10/763,819
Confirmation No.: 5026
Filed: January 23, 2004
For: FABRICATION OF METALLIC MICROSTRUCTURES VIA
EXPOSURE OF PHOTORESISTIVE COMPOSITION
Examiner: K. Duda
Art Unit: 1795

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted via the Office electronic filing system in accordance with § 1.8(a)(4).

Dated: 5/11/08



Angela M. Griffith

TRANSMITTAL LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed are the following items for filing in connection with the above-referenced
Patent Application:

1. Part B - Fee Transmittal;

The amount of \$720.00 covering the required fees is being paid by credit card. The Director is hereby authorized to charge any deficiency or credit any overpayment in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in

this application by this firm) to our Deposit Account No. 23/2825, under Docket No. H0498.70130US01.

Dated: 05/16/08

Respectfully submitted,

By


Timothy J. Oyer, Ph.D.

Registration No.: 16,628

Jessamine M. Lee, Ph.D.

Registration No.: 61,674

WOLF, GREENFIELD & SACKS, P.C.

Federal Reserve Plaza

600 Atlantic Avenue

Boston, Massachusetts 02210-2206

617.646.8000